

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
<b>CONVEYING PARTY DATA</b>													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Yaojian Lin</td> <td>03/02/2010</td> </tr> <tr> <td>Kang Chen</td> <td>03/02/2010</td> </tr> <tr> <td>Jianmin Fang</td> <td>03/02/2010</td> </tr> <tr> <td>Xia Feng</td> <td>03/04/2010</td> </tr> <tr> <td>Xusheng Bao</td> <td>03/02/2010</td> </tr> </tbody> </table>		Name	Execution Date	Yaojian Lin	03/02/2010	Kang Chen	03/02/2010	Jianmin Fang	03/02/2010	Xia Feng	03/04/2010	Xusheng Bao	03/02/2010
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Xusheng Bao	03/02/2010												
<b>RECEIVING PARTY DATA</b>													
Name:	STATS ChipPAC, Ltd.												
Street Address:	10 Ang Mo Kio Street 65												
Internal Address:	#05-17/20 Techpoint												
City:	Singapore												
State/Country:	SINGAPORE												
Postal Code:	569059												
<b>PROPERTY NUMBERS Total: 1</b>													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12720057</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12720057								
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<b>CORRESPONDENCE DATA</b>													
Fax Number:	(602)748-4414												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
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Address Line 4:	Tempe, ARIZONA 85284												
ATTORNEY DOCKET NUMBER:	2515.0243												

OP \$40.00 12720057

**501113425**

**PATENT  
 REEL: 024050 FRAME: 0347**

NAME OF SUBMITTER:

Robert D. Atkins

Total Attachments: 5

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ASSIGNMENT AND AGREEMENT

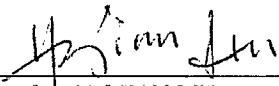
For good and valuable consideration, the receipt of which is hereby acknowledged, I, YAOJIAN LIN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER AROUND SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0243, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

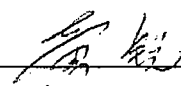
I hereby authorize and request the government authority in the United States to issue patent(s) upon the aforesaid application, continuation, division, reissue, reexamination, extension, renewal, or substitute, to STATS ChipPAC, for the sole use and behalf of STATS ChipPAC, its successors, assigns, and legal representatives, to the full end of the term for which the patent(s) may be granted, the same as they would have been held and enjoyed by me had this assignment not been made. I authorize and request the equivalent authorities in countries foreign to the United States to issue the patents of their respective countries to and in the name of STATS ChipPAC in the same manner.

I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

  
\_\_\_\_\_  
Signature for YAOJIAN LIN

Witnessed on this date: Mar 02 2010

Signature of Witness:   
\_\_\_\_\_

Printed Name of Witness: HUANG RUI

Address of Witness: 5 Yishun Street 23  
Singapore 768862

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KANG CHEN of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER AROUND SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0243, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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Chen Kang  
Signature for KANG CHEN

Witnessed on this date: Mar 02 2010

Signature of Witness: 

Printed Name of Witness: HUANG RUI

Address of Witness: I Yishun Street 23  
Singapore 768442

ASSIGNMENT AND AGREEMENT

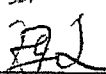
For good and valuable consideration, the receipt of which is hereby acknowledged, I, JIANMIN FANG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER AROUND SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0243, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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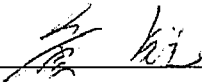
I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

  
\_\_\_\_\_  
Signature for JIANMIN FANG

Witnessed on this date:

Mar 02 2010

Signature of Witness:



Printed Name of Witness:

HUANG RUI

Address of Witness:

5 Yishun Street 23

Singapore 768441

ASSIGNMENT AND AGREEMENT

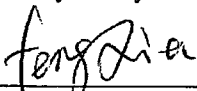
For good and valuable consideration, the receipt of which is hereby acknowledged, I, XIA FENG of Singapore, have sold, assigned, and transferred, and do hereby sell, assign, and transfer unto STATS ChipPAC, Ltd. (STATS ChipPAC), a company formed under the laws of the country of Singapore, having its principal office at 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SEMICONDUCTOR DEVICE AND METHOD OF FORMING INSULATING LAYER AROUND SEMICONDUCTOR DIE, which is described, illustrated, and claimed in any patent application under Attorney Docket No. 2515.0243, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may issue upon such application(s).

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\_\_\_\_\_  
Signature for XIA FENG

Witnessed on this date: Mar 04 2010

Signature of Witness:   
\_\_\_\_\_

Printed Name of Witness: HUANG RUI

Address of Witness: 5 Yishun Street 23  
Singapore 768442

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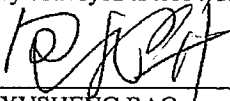
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\_\_\_\_\_  
Signature for XUSHENG BAO

Witnessed on this date: \_\_\_\_\_ Mar 02 2010

Signature of Witness: \_\_\_\_\_ 

Printed Name of Witness: \_\_\_\_\_ HUANG RUI

Address of Witness: \_\_\_\_\_ 5 Yishun Street 23  
Singapore 768442